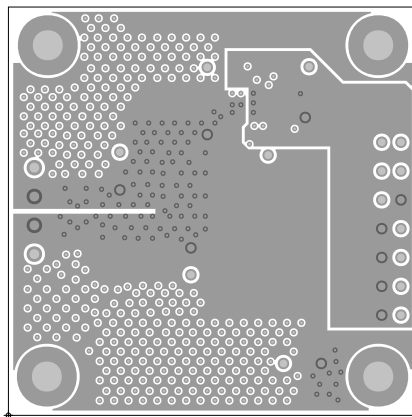
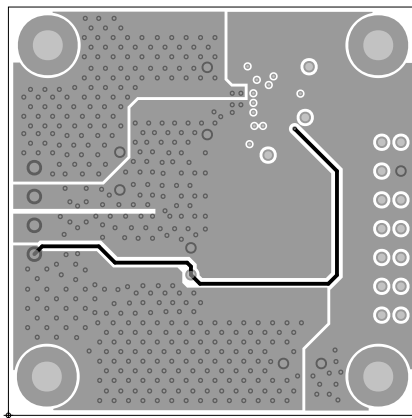


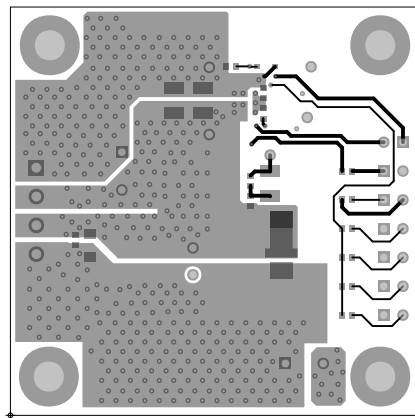
	LAYER: 01 PRIMARY-SIDE	COMPANY NAME: Vishay/Siliconix		UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES
	DESIGNER: TD	PROJECT NAME:		
	CHECKER: INITIAL	SIC46X UNIFIED LOW POWER DEMO		
	DATE: 26AUG17	PROJECT NUMBER:	REV.	
	JOB#:	NUMBER	2	
				TOLERANCES DECIMAL ANGLE X ± .1 ± 5 XX ± .01 MACH FINISH XXX ± .005 ✓



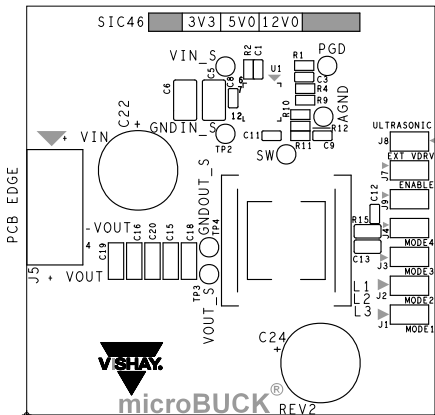
	INNER_LAYER2	COMPANY NAME: Vishay/Siliconix		UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES	
	DESIGNER: TD	PROJECT NAME:			
	CHECKER: INITIAL	SIC46X UNIFIED LOW POWER DEMO		TOLERANCES DECIMAL ANGLE X ± .1 ± 5 XX ± .01 MACH FINISH XXX ± .005 ✓	
	DATE: 26AUG17	PROJECT NUMBER:			
	JOB#:	NUMBER			
			REV. 2		



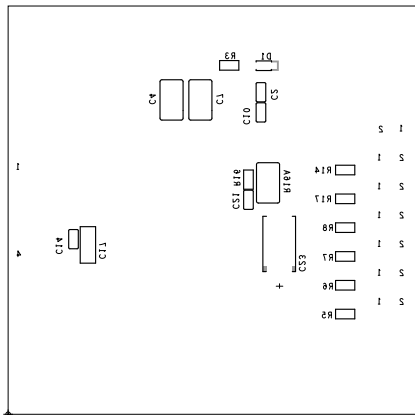
	INNER_LAYER3	COMPANY NAME: Vishay/Siliconix		UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMAL ANGLE X ± .1 ± 5 XX ± .01 MACH FINISH XXX ± .005 ✓
	DESIGNER: TD	PROJECT NAME:		
	CHECKER: INITIAL	SIC46X UNIFIED LOW POWER DEMO		
	DATE: 26AUG17	PROJECT NUMBER:	REV.	
	JOB#:	NUMBER	2	



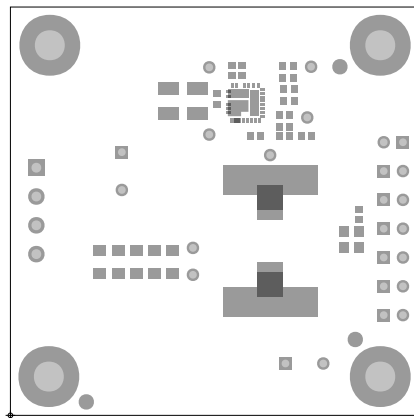
JOB#: DATE: 28AUG17 CHECKER: INITIAL DESIGNER: TD SECONDARY-SIDE LAYER: 04	COMPANY NAME: Vishay Siliconix		UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES
	PROJECT NAME: 21C46X UNIFIED LOW POWER DEMO		
	PROJECT NUMBER: 2	REV. S	
	NUMBER		



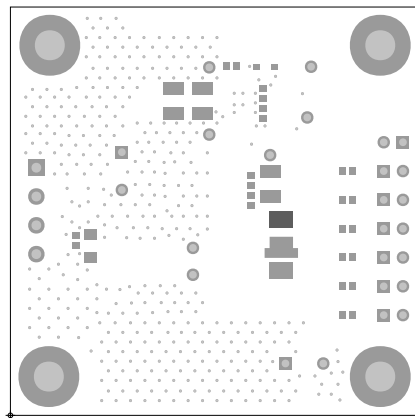
SILKTOP



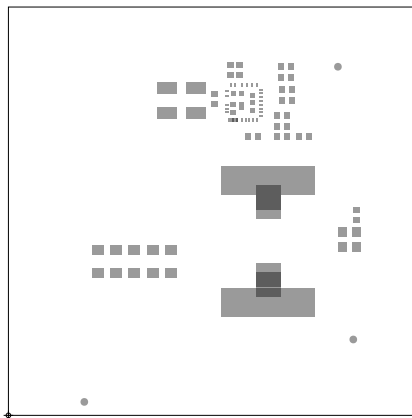
S I L K B O T T O M



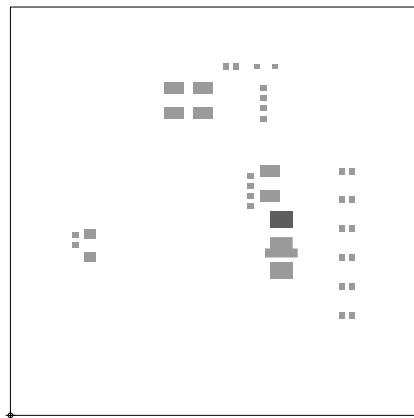
	SOLDERMASK PRIMARY-SIDE	COMPANY NAME: Vishay/Siliconix		UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMAL ANGLE X ± .1 ± 5 XX ± .01 MACH FINISH XXX ± .005 ✓
	DESIGNER: TD	PROJECT NAME:		
	CHECKER: INITIAL	SIC46X UNIFIED LOW POWER DEMO		
	DATE: 26AUG17	PROJECT NUMBER:	REV.	
	JOB#:	NUMBER	2	



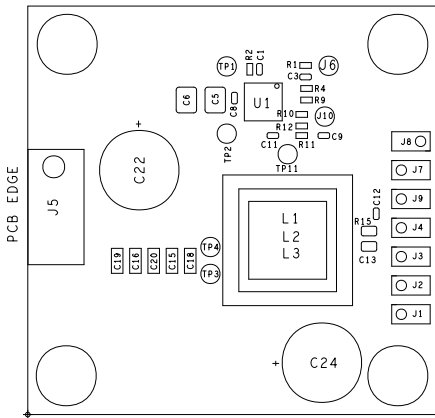
JOB#: DATE: 28AUG17 CHECKER: INITIAL DESIGNER: TD SECONDARY-SIDE SOLDERMASK	COMPANY NAME: Vishay Siliconix	
	PROJECT NAME: 21C48X UNIFIED LOW POWER DEMO	
	PROJECT NUMBER:	REV. 5
	TOLERANCES DECIMAL X ± .1 ANGLE ± 2 MACH FINISH XXX ± .002 ✓	
	UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES	



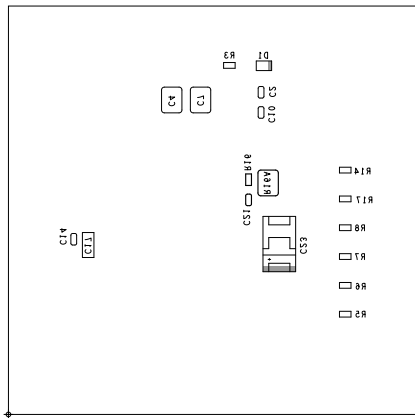
	PASTEMASK PRIMARY-SIDE	COMPANY NAME: Vishay/Siliconix	UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMAL ANGLE X ± .1 ± 5 XX ± .01 MACH FINISH XXX ± .005 ✓
	DESIGNER: TD	PROJECT NAME:	
	CHECKER: INITIAL	SIC46X UNIFIED LOW POWER DEMO	
	DATE: 26AUG17	PROJECT NUMBER:	
	JOB#:	NUMBER	
		REV. 2	



TOLERANCES DECIMAL X ± .1 ANGLE ± .5 MACH FINISH XXX ± .002 ✓	NUMBER		PROJECT NUMBER:	PROJECT NAME:	COMPANY NAME:
	REV.		S	S1C4X UNIFIED LOW POWER DEMO	VISHAY SILICONIX
				CHECKER: INITIAL	PASTEMASK
				DATE: 28AUG17	SECONDARY-SIDE
				DESIGNER: TD	JOB#:

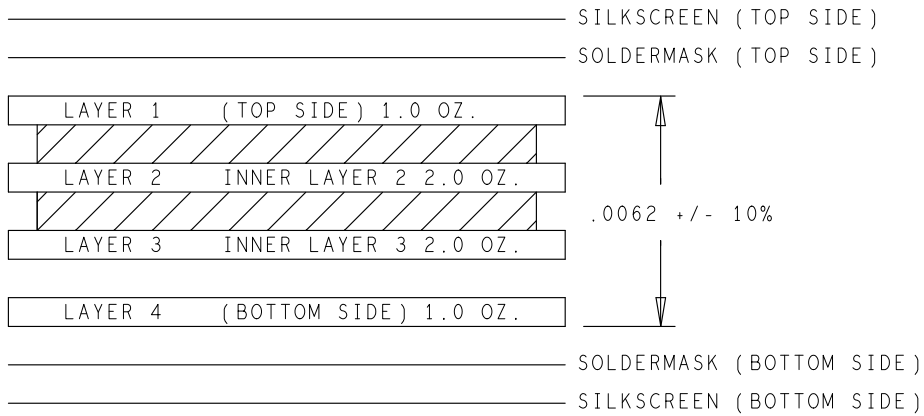


ASSEMBLY TOP

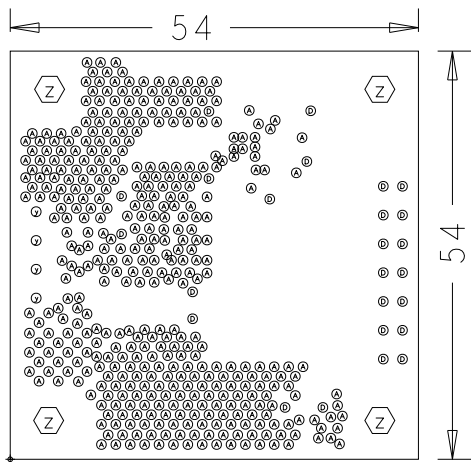


ASSEMBLY BOTTOM

LAYER DETAIL
4 LAYER



DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
⊙	13.0	+3.0/-13.0	PLATED	418
⊙	40.0	+3.0/-3.0	PLATED	25
⊙	51.0	+3.0/-3.0	PLATED	4
⊕	156.0	+3.0/-3.0	PLATED	4



FAB NOTE

REVISIONS

REV	DESCRIPTION	DATE	APPROVED

FAB NOTES:UNLESS OTHERWISE SPECIFIED.

1. PART NUMBER
P/N 133-020-0002
2. SIDE SHOWN
PRIMARY / SIDE 1.
3. DIMENSIONS
DECIMAL INCHES.
4. BASE MATERIAL
LEAD-FREE PROCESS
5. Tg
MINIMUM GLASS TRANSITION TEMPERATURE (Tg) OF 170 DEGREES CELSIUS.
6. FLAME CLASS
UL 94V-0 & MUST MEET REQUIREMENTS OF UL 796.
7. MOT
MANUFACTURE MUST BE UL RECOGNIZED TO PRODUCE THIS PRODUCT SUCH THAT IT MEETS 130 DEGREES CELSIUS MAXIMUM OPERATING TEMPERATURE (MOT).
8. MARKINGS
THE FOLLOWING MUST BE MARKED OR ETCHED ON SIDE 2 OF PCB IN AREA SHOWN:
DATE CODE.
UL RECOGNIZED VENDOR ID UL TYPE DESIGNATION AND/OR MARKINGS WHICH REPECT THE SPECIFIED FLAME CLASS AND MAXIMUM OPERATING TEMPERATURE RATTINGS.
9. PCB THICKNESS
0.62 +/-10% AS MESURED OVER METAL.
- 10.BOW & TWIST
SHALL BE DETERMINED BY PHYSICAL MEASUREMENT AND PERCENTAGE CALCULATION IN ACCORDANCE WITH IPC - TM - 650. METHOD 2.4.22.
- 11.PLATING
MINIMUM COPPER THICKNESS AFTER PROCESSING INTERNAL AND EXTERNAL LAYERS IS PROVIDED BELOW IN THE LAYER STACKUP.
HOLE PLATING = 0.001 MIN. AVERAGE / 0.0008 ABSOLUTE MIN PLATING.
HOLE DIAMETERS SPECIFIED AFTER PLATING (SEE HOLE SCHEDULE).
- 12.CONDUCTORS
FINISHED CONDUCTOR WIDTH: 0.010 REDUCED NO MORE THAN 20% OF NOMINAL.
FINISHED CONDUCTOR SPACING: 0.003 MINIMUM.
- 13.ANNULAR RING
0.001 MINIMUM FOR INTERNAL ANNULAR RING.
0.002 MINIMUM FOR EXTERNAL ANNULAR RING.
- 14.Minimum immersion gold thickness of 2uin - 8uin over a minimum of 118uin electroless nickel.
- 15.When applies Gold Plating and Nickel Plating For Edge-Board Connectors and Non-Soldered Areas Shall be Per IPC-2221
Unless Otherwise Specified on the Fabrication Drawing.
For none functional short gold fingers it is ok to leave the plating trace

16.SOLDER MASK

TO BE IN ACCORDANCE WITH IPC-SM-840C CLASS T.
TYPE: LIQUID PHOTOIMAGEABLE.
BRAND: CIBA-GEIGY PROBIMER 52, 65M, ENTHONE ENPLATE DSR-3241 OR EQUIVALENT.
FINISH: MATTE FINISH PREFERRED.
COLOR: LIGHT BLUE (OR CLOSEST)
REGISTRATION: TO BE WITHIN +/-0.003 OF ITS RESPECTIVE OUTER CIRCUIT LAYERS.
SOLDER MASK ENCROACHMENT ONTO SMT LANDS IS INTENTIONAL
WHERE SUPPLIED DATA DOES NOT PROVIDE CLEARANCE FROM THE PAD.

17.SOLDER MASK COLOR:LIGHT BLUE (OR CLOSEST)

18.FINISH

SOLDER MASK OVER BARE COPPER (SMOBC) WITH
HOT AIR SOLDER LAVELING (HASL).

19.SILKSCREEN

WHITE NONCONDUCTIVE INK.
NO INK TO APPEAR ON EXPOSED COPPER SUCH AS PLATE THROUGH HOLE PADS AND
SURFACE MOUNT LANDS. INK ON SOLDER MASK COVERED PADS IS PERMISSIBLE.

20.LAYER STACKUP

4 LAYERS. SEE STACK-UP DETAIL.

21.TOTAL THICKNESS

0.062".

22.FIDUCIALS

ADD FIDUCIALS TO PRIMARY SIDES.

23 MATERIAL:

LEAD-FREE PROCESS

24 COLOR:

LIGHT BLUE (OR CLOSEST)

25 COPPER THICKNESS: SEE STACK-UP DETAIL.

	FAB DRAWING	COMPANY NAME: Vishay/Siliconix		UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN INCHES TOLERANCES DECIMAL ANGLE XX ± .01 ± .5 XXX ± .005 MACH FINISH ✓
	DESIGNER: TD	PROJECT NAME: SIC46X_UNIFIED_LOW_POWER_DEMO		
	CHECKER: INITIAL			
	DATE: 26AUG17			
	JOB#:	FAB NUMBER: NUMBER	REV. SHEET: 2 1 OF 2	